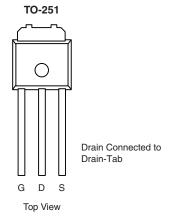


N-Channel 200V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)		
200	0.056 at V _{GS} = 10 V	25		
	0.070 at V _{GS} = 6 V	23		



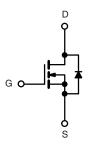
FEATURES

- TrenchFET® Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



APPLICATIONS

· Primary Side Switch



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		V_{DS}	200	V		
Gate-Source Voltage		V_{GS}	± 20	T V		
Continuous Dusin Comment (T. 177 °C)b	T _C = 25 °C	I-	25			
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 125 °C	· I _D	17			
Pulsed Drain Current		I _{DM}	60	Α		
Continuous Source Current (Diode Conduction)		I _S	19			
Avalanche Current		I _{AS}	25			
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	18	mJ		
Maximum Dawar Dissination	T _C = 25 °C	P _D	145 ^b	W		
Maximum Power Dissipation	T _A = 25 °C	T D	3.5 ^a	l vv		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Location to Austrantia	t ≤ 10 s	R _{thJA}	15	18		
Junction-to-Ambient ^a	Steady State	□thJA	40	50	°C/W	
Junction-to-Case (Drain)		R _{thJC}	0.85	1.1		

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. See SOA curve for voltage derating.

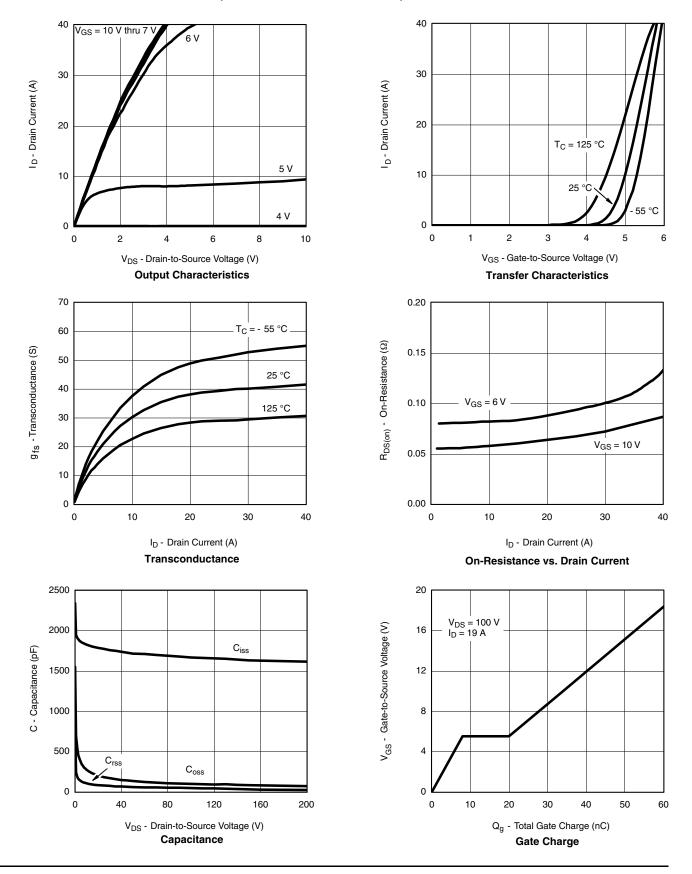


Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS} V _{GS} = 0 V, I _D = 250 μA 200				V		
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2		4	_ v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = 200 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 200 V, V _{GS} = 0 V, T _J = 125 °C			50	50 μΑ	
		V _{DS} = 200 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	40			Α	
		V _{GS} = 10 V, I _D = 5 A		0.056			
D : 0	D	V _{GS} = 10 V, I _D = 5 A, T _J = 125 °C		0.130		Ω	
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 5 A, T _J = 175 °C		0.260			
		V _{GS} = 6 V, I _D = 5 A		0.070			
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 19 A		35		S	
Dynamic ^a							
Input Capacitance	C _{iss}			2400			
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, F = 1 MHz		280		pF	
Reverse Transfer Capacitance	C _{rss}			180			
Total Gate Charge ^c	Q_g			40			
Gate-Source Charge ^c	Q _{gs}	V _{DS} = 100 V, V _{GS} = 10 V, I _D = 19 A		10		nC	
Gate-Drain Charge ^c	Q_{gd}			15			
Gate Resistance	R_g		0.5		2.9	Ω	
Turn-On Delay Time ^c	t _{d(on)}			15	25		
Rise Time ^c	t _r	$V_{DD} = 100 \text{ V}, R_L = 5.2 \Omega$		50	75		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 19 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		30	45	ns	
Fall Time ^c	t _f			60	90		
Source-Drain Diode Ratings and Char	acteristics (7	T _C = 25 °C)					
Pulsed Current	I _{SM}				50	Α	
Diode Forward Voltage ^b	V_{SD}	I _F = 19 A, V _{GS} = 0 V		0.9	1.5	٧	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 19 A, dl/dt = 100 A/μs		180	250	ns	

- Notes: a. Guaranteed by design, not subject to production testing. b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %. c. Independent of operating temperature.

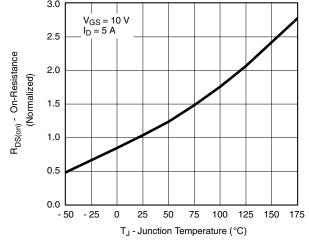


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

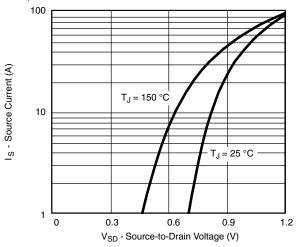




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

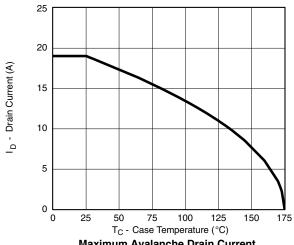


On-Resistance vs. Junction Temperature

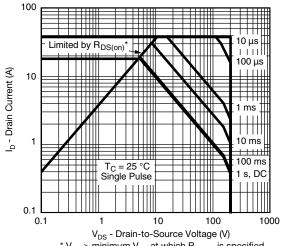


Source-Drain Diode Forward Voltage

THERMAL RATINGS

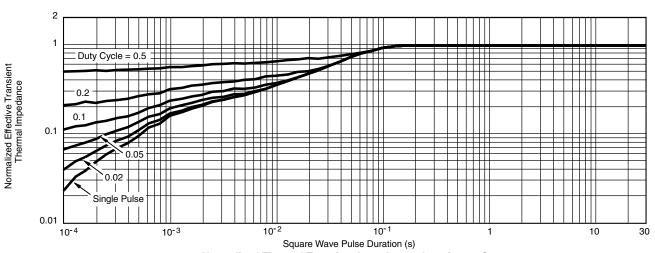


Maximum Avalanche Drain Current vs. Case Temperature



* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

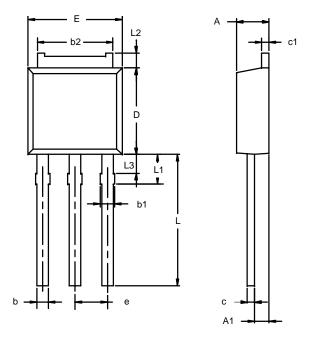
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case



TO-251AA



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	MILLIM	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
E	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090	BSC	
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	



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